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SEMICONDUCTOR DEVICE

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[There are no amendments to this patent.]

Claims

1. Semiconductor device characterized in that it has a structure wherein multiple semiconductor wafers or chips are bonded facing vertically, with it having input/output wiring leads on both sides of the package, and a substrate on which the aforementioned wafers or chips are fastened being supported and sealed by a cap.

2. The semiconductor device described in Claim 1, characterized in that, in the device described in Claim 1, heat-radiating fins or studs are mounted on the package.

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